

L Number	Hits	Search Text	DB	Time stamp
9	2	5834848.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/23 10:28
-	2	20020171157.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/23 10:28
-	0	(257/779 257/738 257/772 257/780 257/782 257/783).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:51
-	0	(257/779 257/738 257/772 257/780 257/782 257/783).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:51
-	775	(257/779).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:52
-	1076	(257/738).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:51
-	356	(257/772).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:52
-	862	(257/780).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:52
-	485	(257/782).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:52
-	736	(257/783).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:52
-	3338	((257/779).CCLS.) ((257/738).CCLS.) ((257/772).CCLS.) ((257/780).CCLS.) ((257/782).CCLS.) ((257/783).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:53
-	2	JP-2000246483-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 13:23
-	1	2000-657021.NRAN.	DERWENT	2003/05/15 13:21
-	1	2000-657021.NRAN.	DERWENT	2003/05/15 13:21
-	0	JP-200023831-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 13:23

-	2	JP-2000223831-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 13:24
-	1	2000-555536.NRAN.	DERWENT	2003/05/15 13:23
-	2	JP-07235565-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 13:24
-	2	6340113.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 13:28
-	23	("4737112" "4740252" "5118029" "5156321" "5248475" "5269453" "5296649" "5299730" "5317191" "5328522" "5385290" "5427865" "5429293" "5540379" "5573602" "5573859" "5591941" "5801446" "5834824" "5885849" "5950908" "6056831" "6077380").PN.	USPAT	2003/05/15 13:30
-	2	6235996.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 14:22
-	81	(copper cu) with ball with (tin Sn) with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 14:23
-	58	(copper cu) with ball with (tin Sn) with bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 14:25
-	1387	(copper cu) with (powder ball) with (tin Sn) and (semiconductor IC chip integrated adj circuit die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 14:29
-	377	((copper cu) with (powder ball) with (tin Sn) and (semiconductor IC chip integrated adj circuit die)) and (copper cu) with (powder ball) with (tin Sn) same (solder bump junction connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 14:38
-	231	((copper cu) with (powder ball) with (tin Sn) and (semiconductor IC chip integrated adj circuit die)) and (copper cu) with (powder ball) with (tin Sn) same (solder bump junction connection)	USPAT	2003/05/15 15:21
-	3	6207259.URPN.	USPAT	2003/05/15 15:17
-	4	("4398975" "4435611" "5117069" "5346750").PN.	USPAT	2003/05/15 15:18
-	5	kazuko.in. and solder	USPAT	2003/05/15 15:21
-	14	bump with plastic adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 10:36
-	94	bump with plastic with (powder particles grain ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 10:37

-	634	solder with plastic with (powder particles grain ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 10:37
-	80	(bump with plastic with (powder particles grain ball)) not (bump with plastic adj ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 10:37
-	1840465	(257/779 257/738 257/772 257/780 257/782 257/783).cccls. "257" "779000" "257" "738000" "257" "772000" "257" "780000" "257" "782000" "257" "783000" Y	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:53